

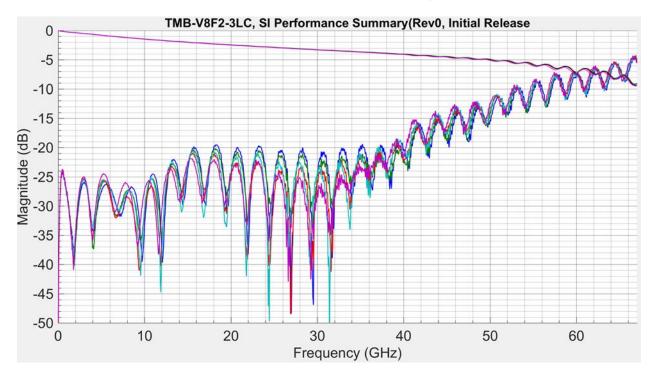
Test and Measurement Performance Report

Part Number TMB-V8F2-3LC

(1.85mm Vertical Launch CPW Solderless Precision Connector) **Distribution**: *Internal & External Use*



SI Performance Summary (Attenuation & Reflections, Single-Ended)



* 10 connectors are shown, measured in pairs. (5 measurements) For further details regarding testing setup, configurations please see the rest of the report.

REVISION:	ECN INFORMATION:	TITLE: 1.85mm Verti	SHEET No.		
1	<u>EC No:</u> N/A	Solderless Precision Connector			1 of 8
	DATE: 04/ 21 / 2020	(TMB-V8F2-3	1010		
DOCUMENT NUMBER:		SI ENGINEER:	DESIGN ENGINEER	ENGINEERING MANAGER	
RSI- TMB_V8F2_3LC		R.Stavoli	P. Volkov	E.Soubh	
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC					

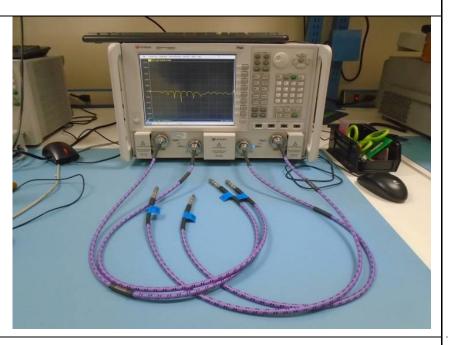


1.0 TEST SETUP AND DUT

Equipment, fixtures, and methods

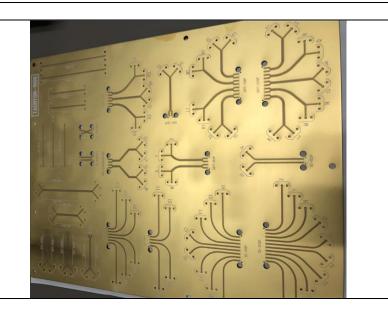
Test method: All data measured from test PCB shown below and a N5227A PNA Network Analyzer

- Calibration was performed up to the
 1. 85mm adapters using calibration
 kit: 85058B
- Data was swept from 10 MHz to 67GHz for 6700 points
- Data averaging was turned off.
- Data is not dembedded and includes the board trace/transition and two RF vertical launch CPW precision connectors



Assembly Description

- T&M PN: TMB-V8F2-3LC
- Carlisle DUT PCB: Core HC 2.5mm CPW Test Board (Rev D0)
- Measured on: 1x Cal Trace (SE-1xCal+)
- Port 1: 1.85mm vertical mount CPW
- Port 2: 1.85mm vertical mount CPW



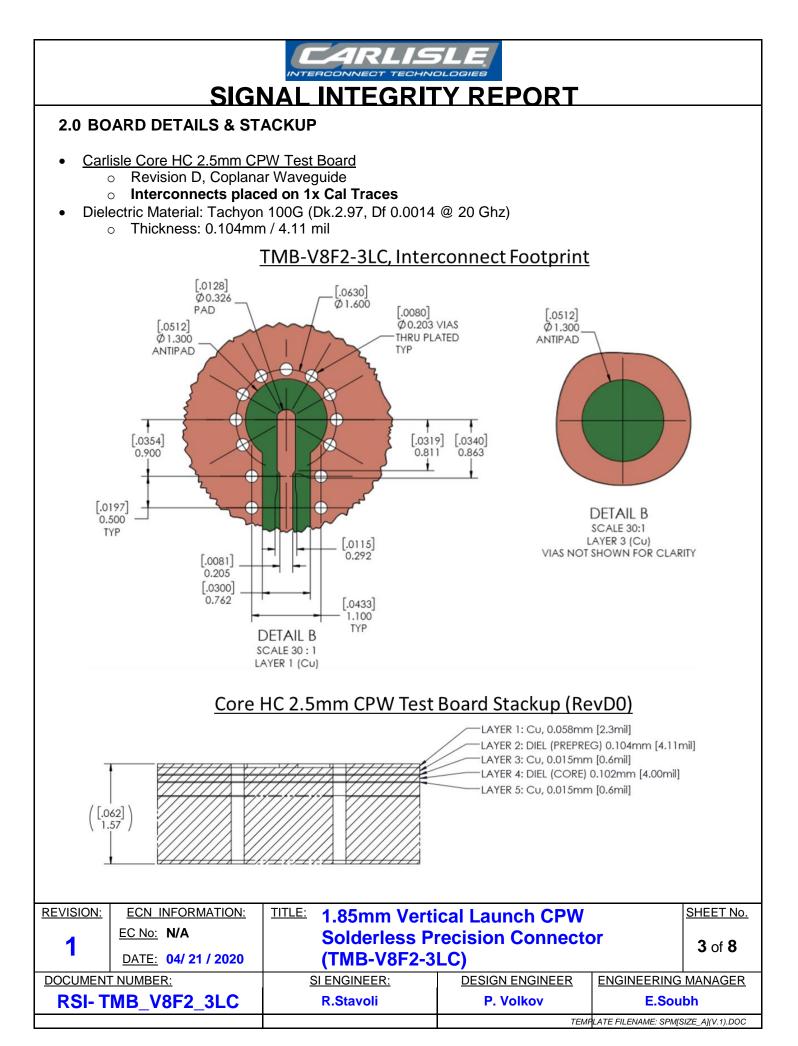
Testing	S	am	ples:	
	-	-		

10 Samples
 5 Channels

5 THRU Measurements (5 Channels = 10 samples) -> -Single-Ended

• 5 Channels

REVISION:	ECN INFORMATION:	TITLE: 1.85mm Vertical Launch CPW			SHEET No.
1	EC No: N/A	Solderless Precision Connector		2 of 8	
· ·	DATE: 04/ 21 / 2020	(TMB-V8F2-3			
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SIGNAL INTEGRITY REPORT

C) PCB FINISH

1. Surface Protective Plating

- a. All exposed copper on the outer layers shall be plated with a protective surface finish.
- b. All exposed pads, edge fingers and plated through holes shall be ENIG with thickness listed in Table 2.

Nickel		Immersion Gold		
µm (microinch)		µm (microinch)		
Min.	Max.	Min.	Max.	
2.5 (100)	13(512)	0.051 (2)	0.2032 (8)	

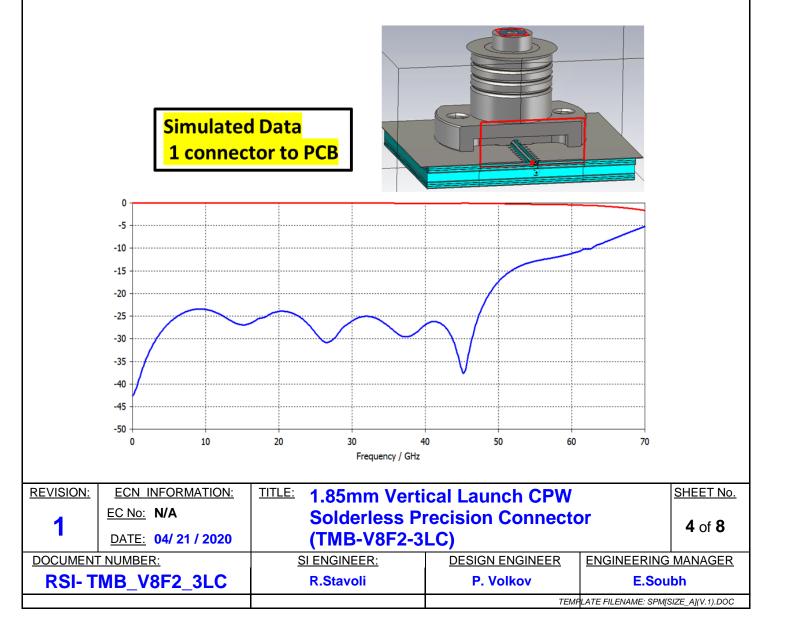
2. Solder Mask

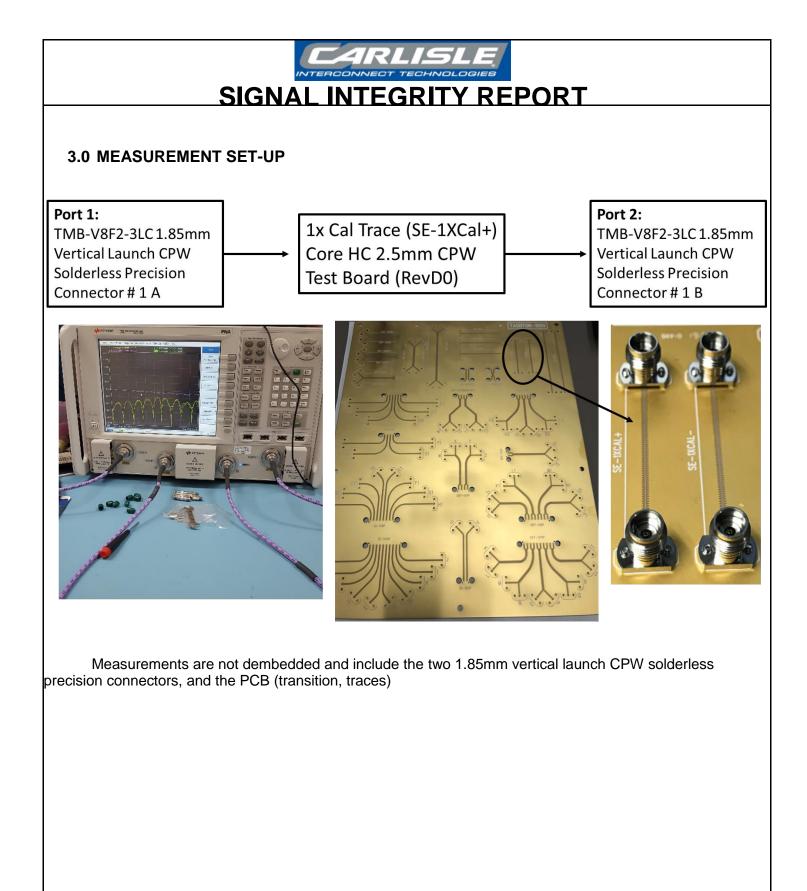
Apply an LPI solder mask to both sides of the board, the solder mask color is defined in the table.

PCB PN	Soldermask color
NA	Green

3. Silkscreen

Silkscreen shall be permanent, non-conductive ink. There shall be no silkscreen on any solderable component pad. Color: White



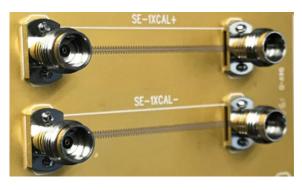


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SIGNAL INTEGRITY REPORT

4.0 SIGNAL INTEGRITY RESULTS (CIT: CORE HC 2.5MM CPW PCB, 1X CAL TRACE)



Insertion Loss (S21), 10 connectors measured, 5 measurements

